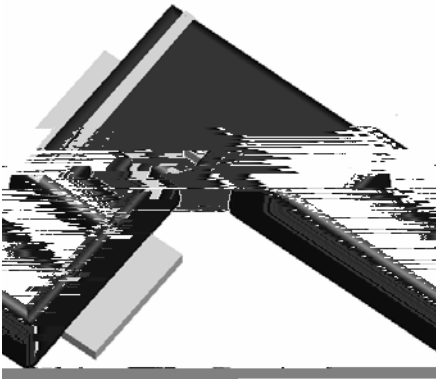
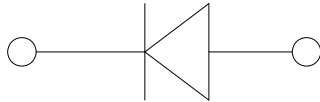




- Low profile package
- Ideal for automated placement
- Glass passivated chip junction
- High forward surge capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

For use in general purpose rectification of power supplies, inverters, converters, and freewheeling diodes for consumer, and telecommunication.



- : SMBF
- Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free
- : Tin plated leads, solderable per J-STD-002 and JESD22-B102
- Cathode line denotes the cathode end

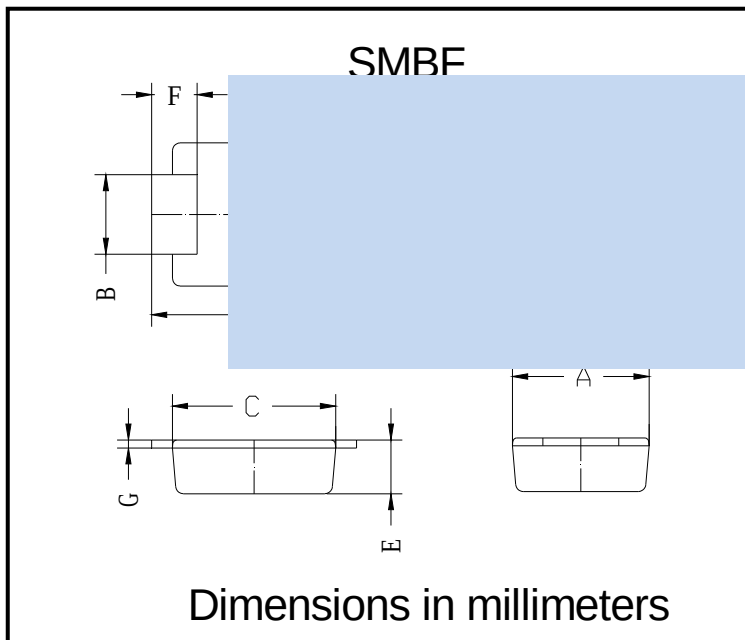
($T_a=25$ Unless otherwise specified)

Device marking code			GS3ABF	GS3BBF	GS3DBF	GS3GBF	GS3JBF	GS3KBF	GS3MBF
Maximum Repetitive peak reverse voltage	V_{RRM}	V	50	100	200	400	600	800	1000
Maximum RMS Voltage	V_{RMS}	V	35	70	140	280	420	560	700
Maximum DC Blocking Voltage	V_{DC}	V	50	100	200	400	600	800	1000
Average rectified output current @60Hz sine wave, resistance load, TL (Fig.1)	I_O	A	3.0						

Forward Surge Current (Non-repetitive)
@60Hz Half-sine wave, 1 cycle, $T_j=25$

	I_{FSM}	A	2	2	2	2	2	2	2
			@1ms, square wave, 1 cycle, $T_j=25$						
Current squared time @1ms≤t≤8.3ms $T_j=25$ Rating of per diode	I^2t	A ² s	41.5						
Typical junction capacitance @Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	C_j	pF	25						
Storage temperature	T_{stg}		-55 ~ +150						
Junction temperature	T_j		-55 ~ +150						

■ (Example)





P1	6.20
P2	2.40



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The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (s